




PCN Number:	20150430001		PCN Date:	4/30/2015																						
Title:	Die Revision Change for select ULN2003A devices																									
Customer Contact:	PCN Manager		Dept:	Quality Services																						
Proposed 1st Ship Date:	7/30/2015	Estimated Sample Availability:	Date provided at sample request.																							
Change Type:																										
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials																					
<input checked="" type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification																					
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process																					
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process																					
<input type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process																					
		<input type="checkbox"/>	Part number change																							
PCN Details																										
Description of Change:																										
This notification is to inform of a die revision change to select devices. The design change does not affect the device's guaranteed datasheet specifications or electrical performance. Affected devices are listed in "Product Affected" section.																										
The Die Revision will change as follows:																										
Current		New																								
Die Revision		Die Revision																								
C/D		F																								
Reason for Change:																										
Improved delivery and continuity of supply																										
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):																										
None																										
Changes to product identification resulting from this PCN:																										
Die Rev designator will change as shown in the table & sample label below:																										
Current		New																								
Die Revision [2P]		Die Revision [2P]																								
C/D		F																								
Sample product shipping label to indicate die rev location (not actual product label)																										
   <table border="0" style="float: right;"> <tr> <td>(1P) SN74LS07NSR</td> <td></td> </tr> <tr> <td>(Q) 2000</td> <td>(D) 0336</td> </tr> <tr> <td>(31T) LOT: 3959047MLA</td> <td></td> </tr> <tr> <td>(4W) TKY (1T) 7523483S12</td> <td></td> </tr> <tr> <td>(P)</td> <td></td> </tr> <tr> <td>(2P) REV:</td> <td>(V) 0033317</td> </tr> <tr> <td>(20L) CSO: SHE</td> <td>(21L) CCO: USA</td> </tr> <tr> <td>(22L) ASO: MLA</td> <td>(23L) ACO: MYS</td> </tr> </table> <table border="1" style="float: left; margin-top: 10px;"> <tr> <td>MADE IN: Malaysia</td> <td>2DC: 20:</td> </tr> <tr> <td>MSL 2 / 260C / 1 YEAR</td> <td>SEAL DT</td> </tr> <tr> <td>MSL 1 / 235C / UNLIM</td> <td>03/29/04</td> </tr> </table> <p>OPT: 39 ITEM: LBL: 5A (L) TO: 1750</p>					(1P) SN74LS07NSR		(Q) 2000	(D) 0336	(31T) LOT: 3959047MLA		(4W) TKY (1T) 7523483S12		(P)		(2P) REV:	(V) 0033317	(20L) CSO: SHE	(21L) CCO: USA	(22L) ASO: MLA	(23L) ACO: MYS	MADE IN: Malaysia	2DC: 20:	MSL 2 / 260C / 1 YEAR	SEAL DT	MSL 1 / 235C / UNLIM	03/29/04
(1P) SN74LS07NSR																										
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MADE IN: Malaysia	2DC: 20:																									
MSL 2 / 260C / 1 YEAR	SEAL DT																									
MSL 1 / 235C / UNLIM	03/29/04																									
Product Affected:																										
ULN2003AD	ULN2003AIDG4	ULN2003AIPWE4	ULN2003ANSR																							
ULN2003ADE4	ULN2003AIDR	ULN2003AIPWG4	ULN2003ANSRE4																							
ULN2003ADG4	ULN2003AIDRE4	ULN2003AIPWR	ULN2003ANSRG4																							
ULN2003ADR	ULN2003AIDRG3	ULN2003AIPWRG4	ULN2003APW																							
ULN2003ADRE4	ULN2003AIDRG4	ULN2003AN	ULN2003APW-P																							
ULN2003ADRG3	ULN2003AIN	ULN2003AN-P2	ULN2003APWG3																							
ULN2003ADRG4	ULN2003AINE4	ULN2003AN-SQ	ULN2003APWG4																							

ULN2003AID	ULN2003AINSR	ULN2003ANE4	ULN2003APWR
ULN2003AIDE4	ULN2003AIPW	ULN2003ANS	ULN2003APWRG4

Qualification Report

ULN2003A Die Rev 'F' (SC2003FHS) in MLA and ASESH TSSOP (PW)
Approved 11/10/2014

Product Attributes

Attributes	Qual Device: ULN2003AIPW	Qual Device: ULN2003AIPWR	Qual Device: ULN2003APW	Qual Device: ULN2003APWR	QBS Product: ULN2003BD	QBS Package: RC4558PWR	QBS Package: RC4558PWR	QBS Package: GD75232PWR
Assembly Site	MLA	ASESH	MLA	ASESH	ASESH	MLA (TIM)	ASE SHANGHAI	ASE SHANGHAI
Package Family	TSSOP	TSSOP	TSSOP	TSSOP	SOIC	TSSOP	TSSOP	TSSOP
Wafer Fab Site	SFAB	SFAB	SFAB	SFAB	SHE SFAB	SFAB	SFAB	SHE
Wafer Fab Process	J11	J11	J11	J11	J1-1	J1-SLM	J1-SLM	-

- QBS: Qual By Similarity
- Qual Devices qualified at LEVEL1-260CG: ULN2003AIPW, ULN2003AIPWR, ULN2003APWR, ULN2003APW, ULN2003APWR

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: ULN2003AIPW	Qual Device: ULN2003AIPWR	Qual Device: ULN2003APW	Qual Device: ULN2003APWR	QBS Product: ULN2003BD	QBS Package: RC4558PWR	QBS Package: RC4558PWR	QBS Package: GD75232PWR
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	-	-	-	1/77/0	1/77/0	3/231/0
AC	Autoclave 121C	96 Hours	-	-	-	-	-	1/77/0	-	-
UHAST	Unbiased HAST 130C/85%RH	96 Hours	-	-	-	-	-	-	1/77/0	3/231/0
TC	Temperature Cycle -55/125C	700 Cycles	-	-	-	-	-	1/77/0	-	-
TC	Temperature Cycle -55/150C	500 Cycles	-	-	-	-	1/77/0	1/77/0	1/77/0	3/231/0
HTSL	High Temp. Storage Bake, 150C	1000 Hours	-	-	-	-	-	1/77/0	1/77/0	-
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	-	-	-	-	-	-	3/231/0
TS	Thermal Shock -65/150C	500 Cycles	-	-	-	-	-	1/77/0	-	3/231/0
HTOL	Life Test, 150C	300 Hours	-	-	-	-	1/77/0	1/77/0	1/77/0	3/231/0
WBP	Bond Pull	Wires	-	-	-	-	1/76/0	-	-	-
SD	Solderability	Post 8 Hours Steam Age	-	-	-	-	-	-	-	3/66/0
PD	Physical Dimensions	--	-	-	-	-	-	-	-	3/15/0
LI	Lead Fatigue	Leads	-	-	-	-	-	-	-	3/66/0
LI	Lead Pull	Leads	-	-	-	-	-	-	-	3/66/0
HBM	ESD - HBM	4000 V	-	-	-	-	1/3/0	-	-	-
CDM	ESD - CDM	1500 V	-	-	-	-	-	-	-	-
LU	Latch-up	(per JESD78)	-	-	-	-	1/6/0	-	-	-
ED	Electrical Characterization	Per Datasheet Parameters	-	-	-	-	Pass	Pass	Pass	-
WBS	Bond Strength	Wires	-	-	-	-	1/76/0	1/76/0	1/76/0	3/231/0
FLAM	Flammability (IEC 695-2-2)	--	-	-	-	-	-	-	-	3/15/0
FLAM	Flammability (UL 94V-0)	--	-	-	-	-	-	-	-	3/15/0
FLAM	Flammability (UL-1694)	--	-	-	-	-	-	-	-	3/15/0

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:
Qualified Pb-Free(SMT) and Green

Qualification Report

ULN2003A Die Rev 'F' (SC2003FHS) in MLA SOP (NS) ULN2003AINSR / ULN2003ANS
Approved 02/11/2015

Product Attributes

Attributes	Qual Device: ULN2003AINSR	Qual Device: ULN2003ANS	QBS Product: ULN2003BD	QBS Product: ULN2003BD..	QBS Product: ULN2003BD..	QBS Product: ULN2003BN	QBS Product: ULN2003BPW	QBS Product: ULN2003BPW.	QBS Package: CABT646ANSR	QBS Package: 2F1177NS	QBS Package: TL092CPS
Assembly Site	MLA	MLA	ASESH	MLA	ASESH	JCET CHUZHOU	ASESH	MLA	MLA	MLA	MLA
Package Family	SOP	SOP	SOIC	SOIC	SOIC	POP	TSSOP	TSSOP	SOP	-	-
Wafer Fab Site	SFAB	SFAB	SHE SFAB	SHE SFAB	SHE SFAB	SHE SFAB	SHE SFAB	SHE SFAB	FFAB	SFAB	SFAB
Wafer Fab Process	J11	J11	J1-1	J1-1	J1-1	J1-1	J1-1	J1-1	ASL2B	O12	J11

- QBS: Qual By Similarity
- Qual Devices qualified at LEVEL1-260CG: ULN2003AINSR, ULN2003ANS

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: ULN2003AINSR	Qual Device: ULN2003ANS	QBS Product: ULN2003BD	QBS Product: ULN2003BD..	QBS Product: ULN2003BD..	QBS Product: ULN2003BN	QBS Product: ULN2003BPW	QBS Product: ULN2003BPW.	QBS Package: CABT646ANSR	QBS Package: 2F1177NS	QBS Package: TL092CPS
AC	Autoclave 121C	96 Hours	-	-	-	-	-	-	-	-	3/231/0	3/231/0	3/231/0
TC	Temperature Cycle, -65/150C	500 Cycles	-	-	1/77/0	-	-	1/77/0	-	-	3/231/0	3/231/0	3/231/0
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	-	-	-	-	-	-	-	3/231/0	-	3/231/0
HTOL	Life Test, 150C	300 Hours	-	-	1/77/0	-	-	-	-	-	-	-	-
WBP	Bond Pull	Wires	-	-	1/76/0	1/76/0	-	1/76/0	1/76/0	1/76/0	-	-	-
HBM	ESD - HBM	4000 V	-	-	1/3/0	-	-	-	-	-	-	-	-
CDM	ESD - CDM	1000 V	-	-	1/3/0	-	-	1/3/0	-	-	-	-	-
LU	Latch-up	(per JESD78)	-	-	1/6/0	-	-	-	-	-	-	-	-
ED	Electrical Characterization	Per Datasheet Parameters	-	Pass	Pass	-	Pass	-	-	-	-	-	-
WBS	Bond Strength	Wires	-	-	1/76/0	1/76/0	-	1/76/0	1/76/0	1/76/0	-	-	-

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:
Qualified Pb-Free(SMT) and Green

Qualification Report

ULN2003A Die Rev 'F' (SC2003FHS) in PDIP (N), ULN2003AIN / ULN2003AN
Approved 01/30/2015

Product Attributes

Attributes	Qual Device: ULN2003AIN	Qual Device: ULN2003AIN	Qual Device: ULN2003AN	Qual Device: ULN2003AN	QBS Product: ULN2003BD	QBS Product: ULN2003BD	QBS Product: ULN2003BD..	QBS Product: ULN2003BN	QBS Product: ULN2003BPW	QBS Product: ULN2003BPW.	QBS Product: ULN2003BPW.	QBS Package: SN74HC273N-P2	QBS Package: ULN2003AN	QBS Package: NE5532P	QBS Package: ULN2003AN	QBS Package: SN74HC594N	QBS Package: CD4051BE	QBS Package: ULN2003AN
Assembly Site	MLA	FMX	JCET CHUZHOU	NFME	ASESH	MLA	ASESH	JCET CHUZHOU	ASESH	MLA	MLA	MLA	FMX	FMX	FMX	NFME	JCET CHUZHOU	JCET CHUZHOU
Package Family	PDIP	PDIP	PDIP	N	SOIC	SOIC	SOIC	PDIP	TSSOP	TSSOP	PDIP	PDIP	PDIP	PDIP	PDIP	PDIP	PDIP	PDIP
Wafer Fab Site	SFAB	SFAB	SFAB	SFAB	SHE SFAB	SHE SFAB	SHE SFAB	SHE SFAB	SHE SFAB	SHE SFAB	SHE SFAB	SFAB	SFAB	SFAB	SFAB	SHE SFAB	SFAB	SFAB
Wafer Fab Process	J11	J11	J11	J11	J1-1	J1-1	J1-1	J1-1	J1-1	J1-1	J1-1	74HC-NONEPI	J11	J1-SLM	J1-SLM	HC-MOS	HC-C	J11

- QBS: Qual by Similarity
- Qual Devices qualified at LEVEL-1-260C: ULN2003AIN, ULN2003AN

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: ULN2003AIN	Qual Device: ULN2003AIN	Qual Device: ULN2003AN	Qual Device: ULN2003AN	QBS Product: ULN2003BD	QBS Product: ULN2003BD..	QBS Product: ULN2003BN	QBS Product: ULN2003BPW	QBS Product: ULN2003BPW.	QBS Package: SN74HC273N-P2	QBS Package: ULN2003AN	QBS Package: NE5532P	QBS Package: ULN2003AN	QBS Package: SN74HC594N	QBS Package: CD4051BE	QBS Package: ULN2003AN
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	-	-	-	-	-	-	-	-	3/231/0	1/77/0	1/77/0	3/231/0	3/231/0	3/231/0
AC	Autoclave 121C	96 Hours	-	-	-	-	-	-	-	-	-	1/77/0	-	1/77/0	1/77/0	-	3/231/0	-
UHAST	Unbiased HAST 130C/85%RH	96 Hours	-	-	-	-	-	-	-	-	-	-	-	-	-	3/231/0	-	-
TC	Temperature Cycle, -55/150C	500 Cycles	-	-	-	-	1/77/0	-	1/77/0	-	-	1/77/0	-	1/77/0	1/77/0	3/231/0	3/231/0	-
HTSL	High Temp. Storage Bake, 150C	1000 Hours	-	-	-	-	-	-	-	-	-	-	-	-	-	3/231/0	-	-
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	-	-	-	-	-	-	-	-	1/77/0	-	1/77/0	1/77/0	-	3/231/0	-
TS	Thermal Shock - 55/150C	500 cycles	-	-	-	-	-	-	-	-	-	-	-	1/77/0	1/77/0	3/231/0	-	-
HTOL	Life Test, 150C	300 Hours	-	-	-	-	1/77/0	-	-	-	-	-	-	1/77/0	1/77/0	3/231/0	3/231/0	-
WBS	Bond Pull	Wires	-	-	-	-	-	-	-	-	-	-	-	-	-	3/231/0	3/228/0	3/228/0
WBP	Bond Pull	Wires	-	-	-	-	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	-	-	-	-	3/228/0	3/228/0
SD	Solderability	8 Hours Steam Age	-	-	-	-	-	-	-	-	-	-	-	-	-	-	3/66/0	-
PD	Physical Dimensions	--	-	-	-	-	-	-	-	-	-	-	-	-	-	-	3/15/0	-
LI	Lead Fatigue	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	3/66/0	-
LI	Lead Fatigue	Leads	-	-	-	-	-	-	-	-	-	-	-	-	-	-	3/66/0	-
HBM	ESD - HBM	4000 V	-	-	-	-	1/3/0	-	-	-	-	-	-	-	-	-	-	-
CDM	ESD - CDM	1000 V	-	-	-	-	1/3/0	-	-	1/3/0	-	-	-	-	-	-	-	-
LU	Latch-up (per JEDEC78)	-	-	-	-	-	1/6/0	-	-	-	-	-	-	-	-	-	-	-
ED	Electrical Characterization	Per Datasheet Parameters	Pass	Pass	-	Pass	Pass	-	Pass	-	-	Pass	-	Pass	Pass	Pass	Pass	Pass
WBS	Bond Strength	Wires	-	-	-	-	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	-	-	1/76/0	1/76/0	3/234/0	-	-
LI	Lead Pull to Destruction	Leads	-	-	-	-	-	-	-	-	-	-	-	-	-	-	3/66/0	-
LI	Lead Pull	Leads	-	-	-	-	-	-	-	-	-	-	-	-	-	3/66/0	-	-
FLAM	Flammability (EC 695-2-2)	--	-	-	-	-	-	-	-	-	-	-	-	-	-	3/15/0	3/15/0	-
FLAM	Flammability (UL 94V-0)	--	-	-	-	-	-	-	-	-	-	-	-	-	-	3/15/0	3/15/0	-
FLAM	Flammability (UL-1694)	--	-	-	-	-	-	-	-	-	-	-	-	-	-	3/15/0	3/15/0	-

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JEDEC47: -55C/125C/100 Cycles and -55C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:
Qualified Pb-Free(SMT) and Green

Qualification Report

ULN2003A Die Rev 'F' (SC2003FHS) in SO(C)D

Approved 01/21/2015

Product Attributes

Die Attributes	Qual Device: ULN2003AD	Qual Device: ULN2003AD	Qual Device: ULN2003ADR	QBS Product: ULN2003D	QBS Product: ULN2003D	QBS Product: ULN2003D	QBS Product: ULN2003EN	QBS Product: ULN2003BPW	QBS Product: ULN2003BPW.	QBS Product: ULN2003BPW.	QBS Package: CD4053BMS6	QBS Package: LM339DR	QBS Package: RC4558DR	QBS Package: SN74LV14ADR	QBS Package: MA3232DR	QBS Package: RC4558DR	QBS Package: SN74LV14ADR	QBS Package: ULN2003ADR	QBS Package: CD4053BMS6	QBS Package: LM339DR	QBS Package: TL494DR	QBS Package: ULN2003ADR
Wafer Fab Site	F	F	F	F	F	E	F	F	F	F	A	E	B	H	B	B	H	C	A	E	H	C
Wafer Fab Process	SFAB	SFAB	SFAB	SHE SFAB	SHE SFAB	SHE SFAB	SHE SFAB	SHE SFAB	SHE SFAB	SHE SFAB	SFAB	SFAB	SFAB	SFAB	SFAB	SFAB	SFAB	SFAB	SFAB	SFAB	SFAB	SFAB
Wafer Fab Process	J11	J11	J11	J1-1	J1-1	J1-1	J1-1	J1-1	J1-1	J1-1	CD4K	J1-SLM	J1-SLM	ERIC1-S_SLM	LBC3S	J1-LN	ERIC1-S_SLM	J1-SLM	CD4K	J1-SLM 20K	J1-LN 55K	J1-SLM 20K

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: ULN2003AD	Qual Device: ULN2003AD	Qual Device: ULN2003ADR	QBS Product: ULN2003D	QBS Product: ULN2003D	QBS Product: ULN2003D	QBS Product: ULN2003EN	QBS Product: ULN2003BPW	QBS Product: ULN2003BPW.	QBS Product: ULN2003BPW.	QBS Package: CD4053BMS6	QBS Package: LM339DR	QBS Package: RC4558DR	QBS Package: SN74LV14ADR	QBS Package: MA3232DR	QBS Package: RC4558DR	QBS Package: SN74LV14ADR	QBS Package: ULN2003ADR	QBS Package: CD4053BMS6	QBS Package: LM339DR	QBS Package: TL494DR	QBS Package: ULN2003ADR			
HAST	Biased HAST, 130C/85%RH	96 hours	-	-	-	-	-	-	-	-	-	1/77/0	1/77/0	1/77/0	1/77/0	3/231/0	1/77/0	1/77/0	1/77/0	1/77/0	1/77/0	1/77/0	1/77/0	3/229/0	1/77/0		
AC	Autoclave 121C	96 hours	-	-	-	-	-	-	-	-	-	-	-	-	-	3/231/0	1/77/0	1/77/0	1/77/0	1/77/0	1/77/0	1/77/0	1/77/0	3/231/0	3/231/0		
UHAST	Unbiased HAST 130C/85%RH	96 hours	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-		
TC	Temperature Cycle, -55/150C	500 Cycles	-	-	-	1/77/0	-	1/77/0	-	-	-	1/77/0	1/77/0	1/77/0	1/77/0	3/231/0	3/231/0	3/231/0	3/231/0	3/231/0	3/231/0	3/231/0	3/231/0	3/231/0	3/231/0		
HTSL	High Temp. Storage Bake, 150C	1000 Hours	-	-	-	-	-	-	-	-	1/77/0	1/77/0	1/77/0	1/77/0	-	3/231/0	3/231/0	-	-	-	-	-	-	-	-		
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	-	-	-	-	-	-	-	-	-	-	-	3/231/0	-	-	3/231/0	1/77/0	1/77/0	-	-	-	-	-		
TS	Thermal Shock - 55/150C	500 cycles	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	1/77/0	3/231/0	3/231/0	3/231/0	3/231/0	3/231/0		
HTOL	Life Test, 150C	300 Hours	-	-	-	1/77/0	-	-	-	-	1/77/0	1/77/0	1/77/0	1/77/0	3/231/0	1/77/0	1/77/0	1/77/0	1/77/0	1/77/0	1/77/0	1/77/0	1/77/0	3/231/0	3/231/0		
WBP	Bond Pull	Wires	-	-	-	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	3/229/0	1/76/0	
HBM	ESD - HBM	4000 V	-	-	-	1/3/0	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	
CDM	ESD - CDM	1000 V	-	-	-	1/3/0	-	-	-	1/3/0	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	
LU	Latch-up (per JEDEC78)	-	-	-	-	1/6/0	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	
ED	Electrical Characterization	Per Datasheet Parameters	-	-	-	Pass	Pass	-	Pass	Pass	Pass	Pass	Pass	Pass	Pass	Pass	Pass	Pass	Pass	Pass	Pass	Pass	Pass	Pass	Pass	Pass	
WBS	Bond Strength	Wires	-	-	-	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	1/76/0	3/229/0	1/76/0
LI	Lead Pull to Destruction	Leads	-	-	-	-	-	-	-	-	-	-	-	-	-	3/66/0	1/22/0	1/22/0	-	-	-	-	-	-	-	-	
LI	Lead Pull	Leads	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	1/22/0	1/22/0	3/66/0	3/66/0	-	-	-	
FLAM	Flammability (EC 695-2-2)	--	-	-	-	-	-	-	-	-	-	-	-	-	-	3/15/0	1/5/0	1/5/0	-	-	-	-	-	-	3/15/0	-	
FLAM	Flammability (UL 94V-0)	--	-	-	-	-	-	-	-	-	-	-	-	-	-	3/15/0	1/5/0	1/5/0	-	-	-	-	-	-	3/15/0	-	
FLAM	Flammability (UL-1694)	--	-	-	-	-	-	-	-	-	-	-	-	-	-	3/15/0	1/5/0	1/5/0	-	-	-	-	-	-	3/15/0	-	

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JEDEC47: -55C/125C/100 Cycles and -55C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:
Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

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